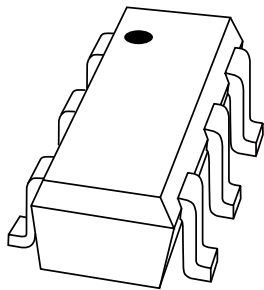


# DATA SHEET



## **BGA2012** 1900 MHz high linear low noise amplifier

Product specification  
Supersedes data of 2000 Sep 06

2000 Dec 04



# 1900 MHz high linear low noise amplifier

# BGA2012

## FEATURES

- Low current, low voltage
- High linearity
- High power gain
- Low noise
- Integrated temperature compensated biasing
- Control pin for adjustment bias current.

## APPLICATIONS

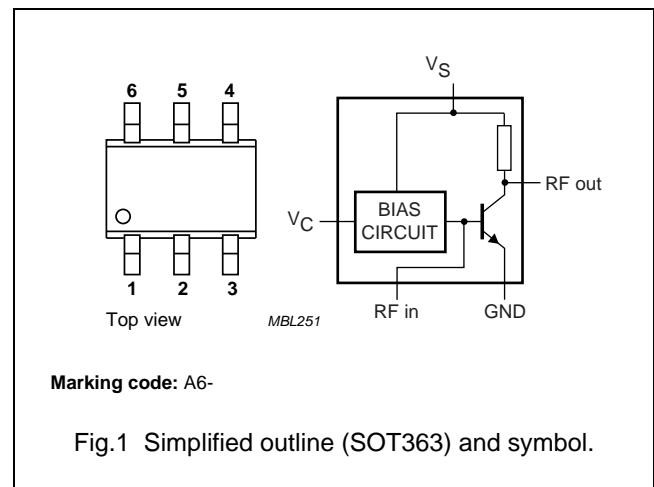
- RF front end
- Low noise amplifiers, e.g. CDMA, PHs, Dect, etc.

## DESCRIPTION

Silicon Monolithic Microwave Integrated Circuit (MMIC) amplifier consisting of an NPN double polysilicon transistor with integrated biasing for low voltage applications in a 6-pin SOT363 plastic SMD package.

## PINNING

PIN	DESCRIPTION
1	RF in
2	V <sub>C</sub>
3	V <sub>S</sub>
4	RF out
5, 6	GND



## QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V <sub>S</sub>	DC supply voltage	RF input AC coupled	3	4.5	V
I <sub>S</sub>	DC supply current		7.5	–	mA
I <sub>C</sub>	DC control current	V <sub>C</sub> = V <sub>S</sub>	0.11	–	mA
S <sub>21</sub>   <sup>2</sup>	insertion power gain	in application circuit, see Fig.2; f = 1900 MHz	16	–	dB
NF	noise figure	I <sub>S</sub> = 7 mA; f = 1900 MHz	1.7	–	dB

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134)

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>S</sub>	DC supply voltage	RF input AC coupled	–	4.5	V
V <sub>C</sub>	voltage on control pin		–	V <sub>S</sub>	V
I <sub>S</sub>	supply current	forced by DC voltage on RF input	–	15	mA
I <sub>C</sub>	control current		–	0.25	mA
P <sub>tot</sub>	total power dissipation	T <sub>S</sub> ≤ 100 °C	–	70	mW
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	operating junction temperature		–	150	°C

## 1900 MHz high linear low noise amplifier

BGA2012

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th\ j-s}$	thermal resistance from junction to solder point	$P_{tot} = 135\text{ mW}; T_s \leq 100\text{ }^\circ\text{C}$	350	K/W

## CHARACTERISTICS

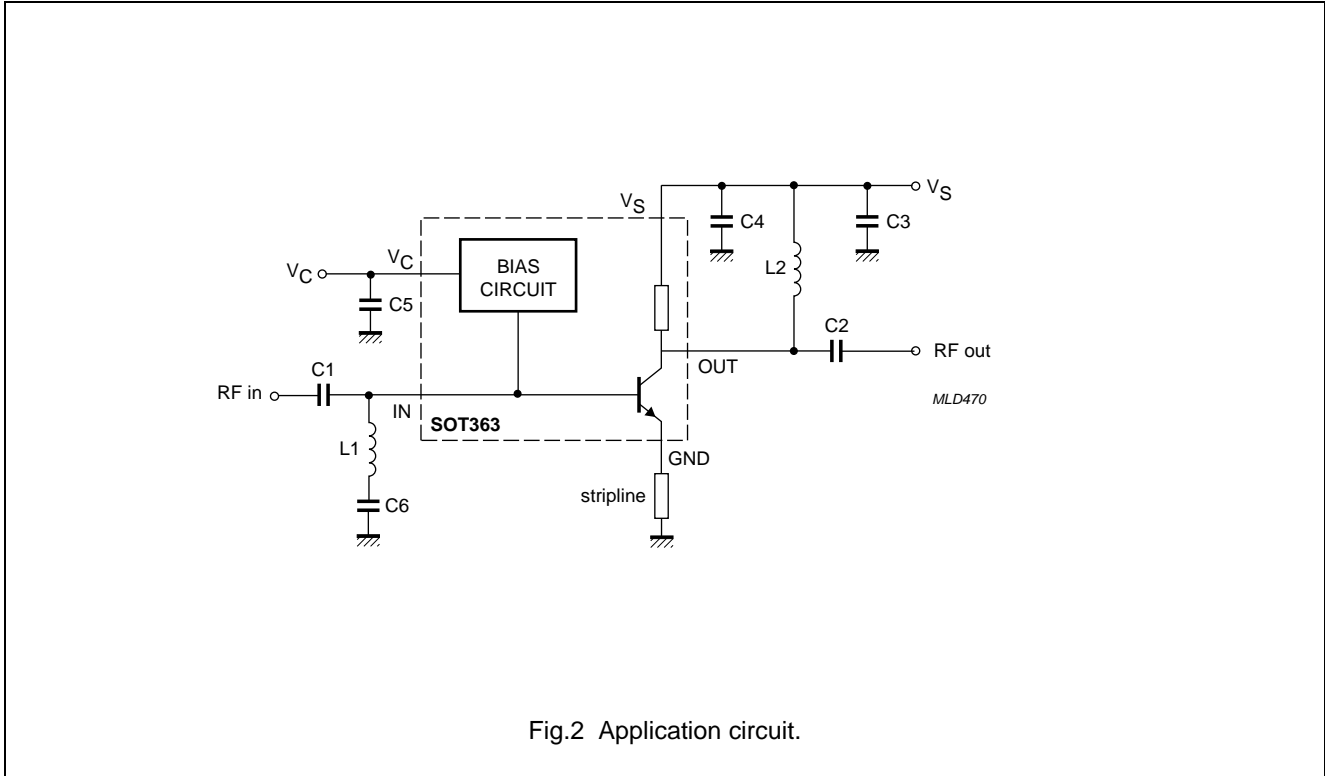
RF input AC coupled;  $V_S = 3\text{ V}; I_S = 7\text{ mA}; f = 1900\text{ MHz}; T_j = 25\text{ }^\circ\text{C}$ ; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
$I_S$	supply current		5	7.5	10	mA
$I_C$	control current		–	0.11	–	mA
$R_{L\ IN}$	return losses input	typical application; see Fig.2	–	–11	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	–20	–	dB
		high IP3 (see Fig.2; stripline = 0.5 mm)	–	–14	–	dB
$R_{L\ OUT}$	return losses output	typical application; see Fig.2	–	–9	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	–10	–	dB
		high IP3 (see Fig.2; stripline = 0.5 mm)	–	–8	–	dB
$ S_{21} ^2$	insertion power gain	typical application (see Fig.2)	–	14	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	16	–	dB
		high IP3 (see Fig.2; stripline = 0.5 mm)	–	14	–	dB
NF	noise figure	typical application; see Fig.2; $I_S = 7\text{ mA}$	–	1.7	–	dB
		high IP3 (see Fig.2; stripline = 0 mm)	–	2.2	–	dB
		high IP3 (see Fig.2; stripline = 0.5 mm)	–	2.3	–	dB
$IP3_{in}$	input intercept point	typical application; see Fig.2	–	–7	–	dBm
		high IP3 (see Fig.2; stripline = 0 mm)	–	7	–	dBm
		high IP3 (see Fig.2; stripline = 0.5 mm)	–	10	–	dBm

1900 MHz high linear low noise amplifier

BGA2012

APPLICATION INFORMATION



List of components (see Fig.2)

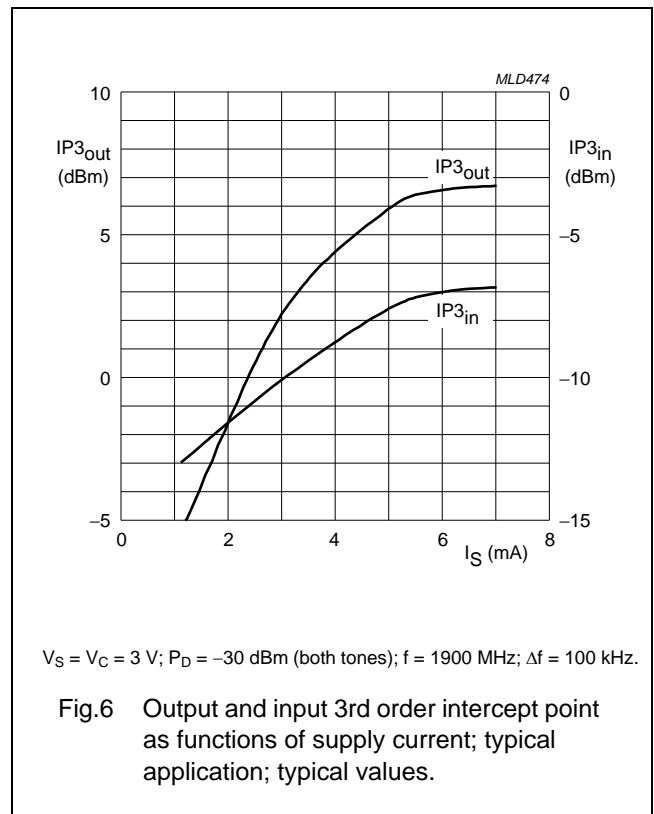
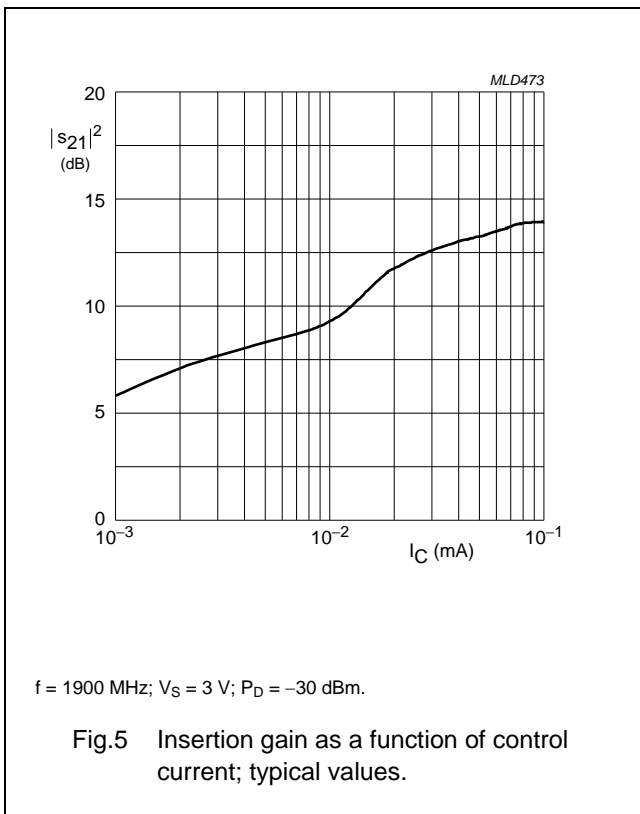
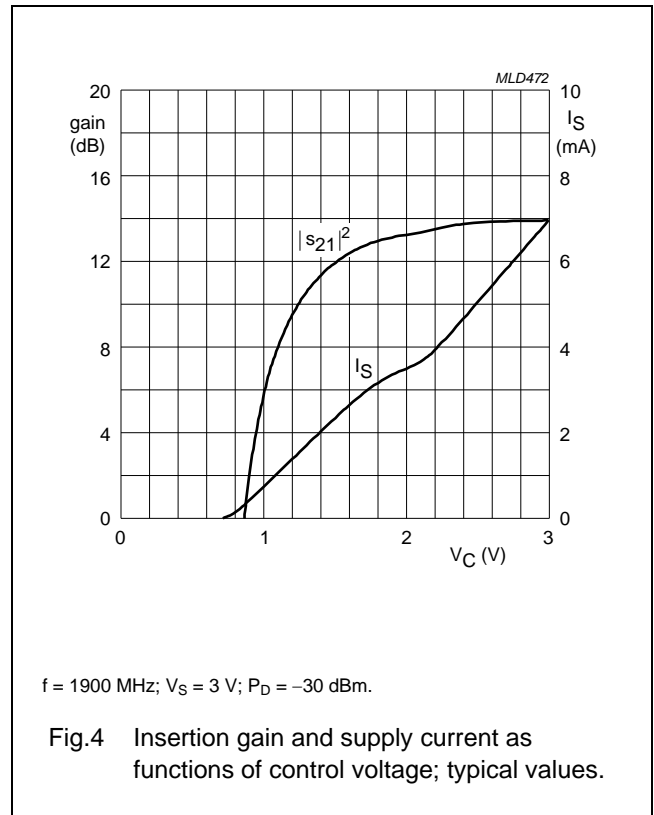
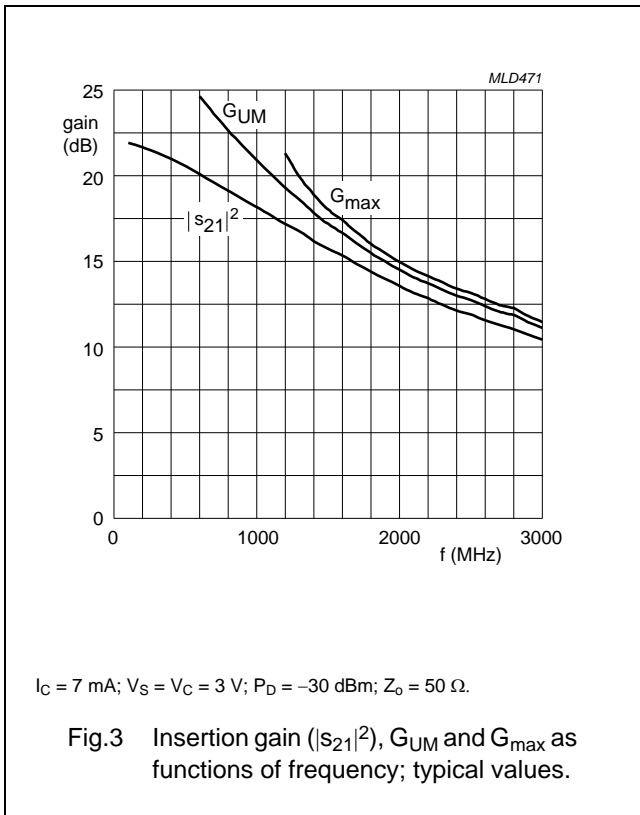
COMPONENT	DESCRIPTION	TYPICAL APPLICATION	HIGH IP3 APPLICATION	DIMENSIONS
C1, C2	multilayer ceramic chip capacitor	100 pF	100 pF	0603
C3, C5	multilayer ceramic chip capacitor	22 nF	22 nF	0603
C4	multilayer ceramic chip capacitor	–	–	–
C6	multilayer ceramic chip capacitor	–	100 nF	0805
L1	SMD inductor	–	3.9 nH	0603
L2	SMD inductor	–	3.9 nH	0603

Note

- The stripline (w = 0.7 mm) is on a gold plated double copper-clad printed-circuit board ( $\epsilon_r = 6.15$ ), board thickness = 0.64 mm, copper thickness = 35  $\mu\text{m}$ , gold thickness = 5  $\mu\text{m}$ .

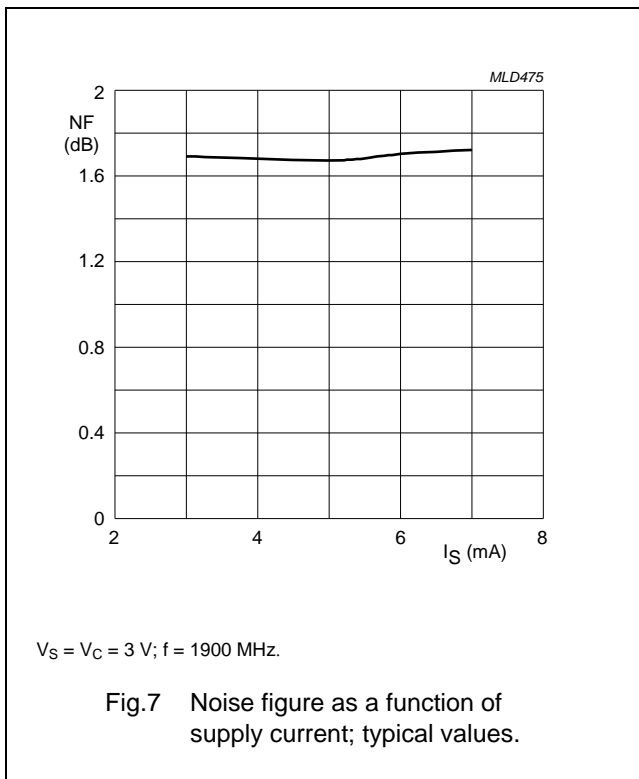
1900 MHz high linear low noise amplifier

BGA2012



1900 MHz high linear low noise amplifier

BGA2012



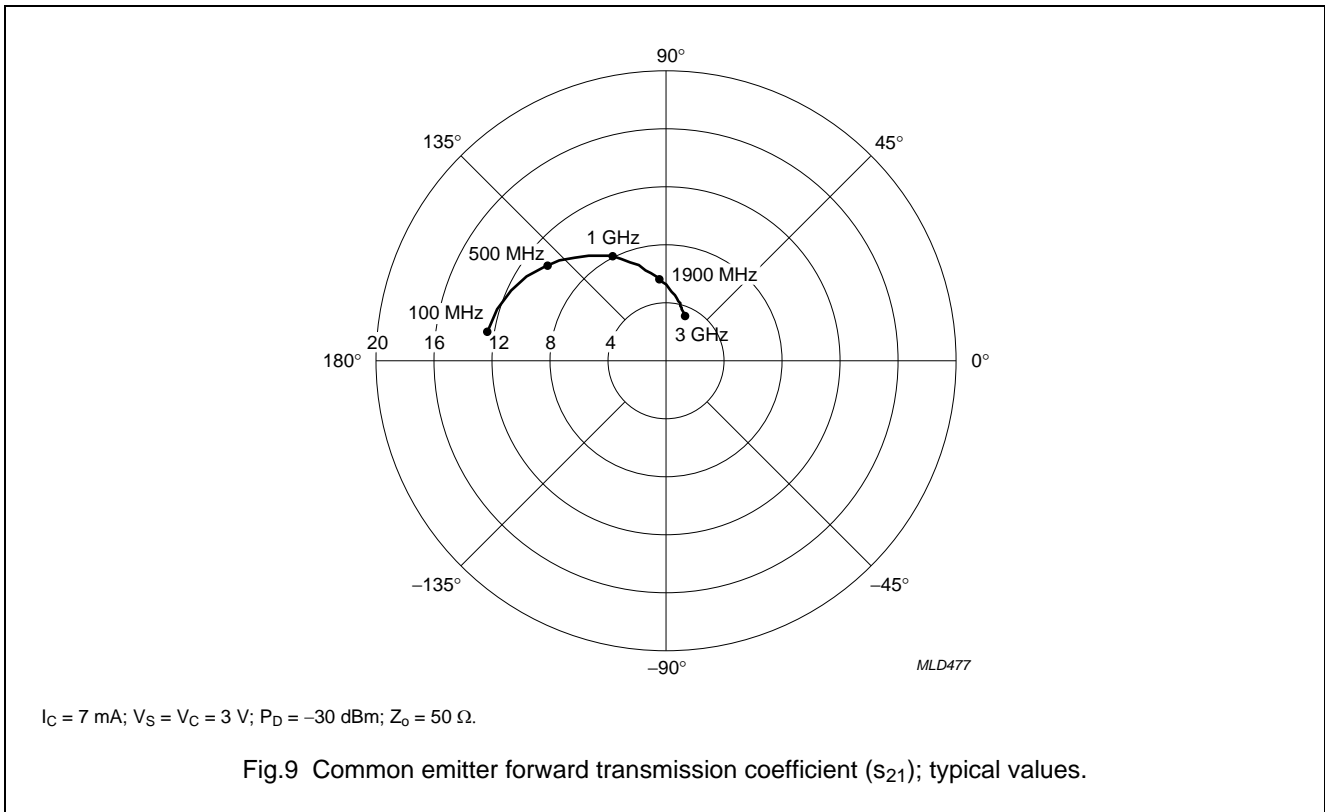
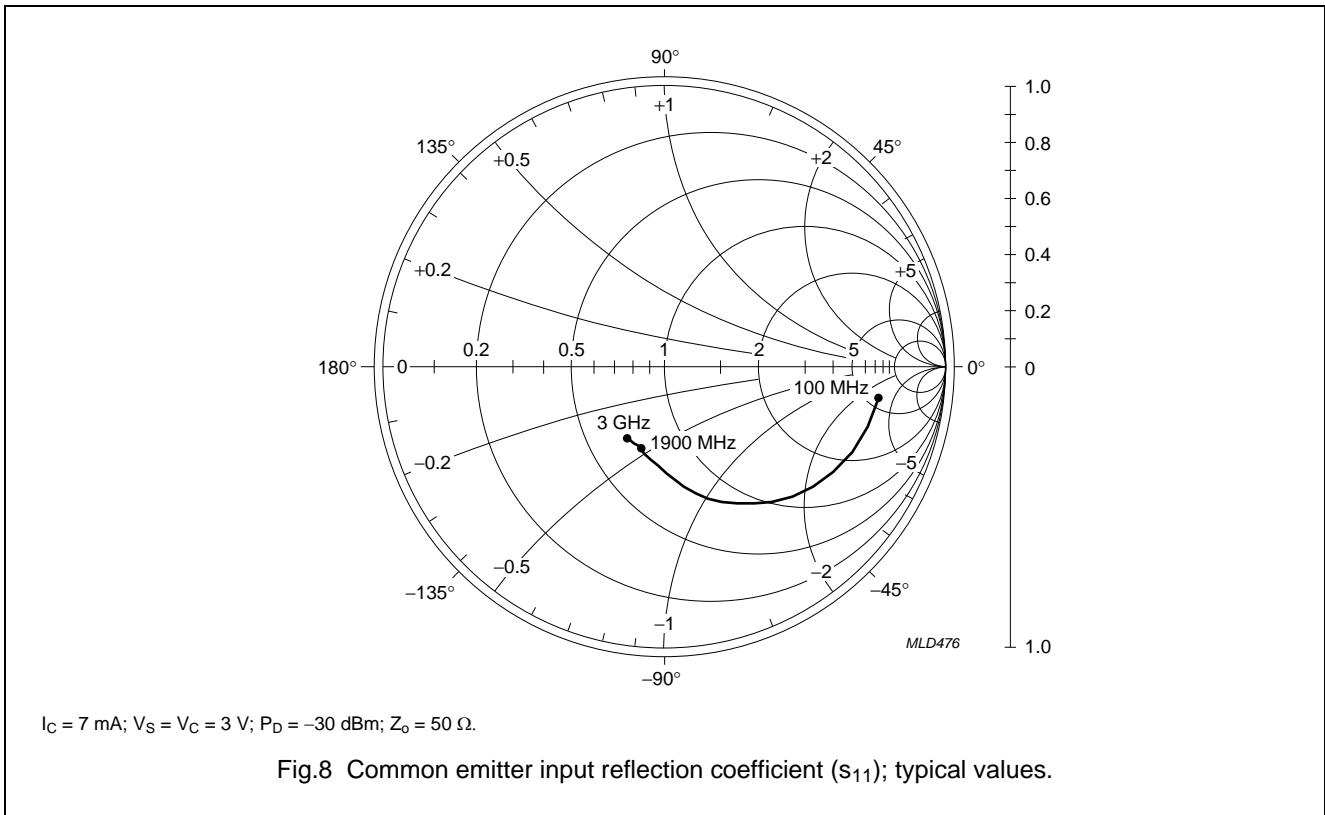
Scattering parameters

$V_S = V_C = 3\text{ V}; P_D = -30\text{ dBm}; Z_0 = 50\ \Omega; T_{amb} = 25\text{ }^\circ\text{C}$

f (MHz)	S <sub>11</sub>		S <sub>21</sub>		S <sub>12</sub>		S <sub>22</sub>	
	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)	MAGNITUDE (ratio)	ANGLE (deg)
100	0.775	-8.390	12.527	171.1	0.005	84.90	0.742	-6.684
200	0.761	-16.37	12.154	163.1	0.011	79.39	0.731	-13.15
400	0.709	-31.51	11.213	148.6	0.020	72.23	0.689	-24.85
600	0.646	-44.97	10.139	136.4	0.028	66.03	0.631	-34.90
800	0.581	-56.47	9.061	126.1	0.034	61.82	0.573	-43.40
1000	0.519	-66.59	8.131	117.3	0.039	58.86	0.519	-50.54
1200	0.461	-75.41	7.254	109.5	0.043	58.07	0.469	-57.19
1400	0.401	-83.99	6.461	103.1	0.047	57.92	0.428	-64.08
1600	0.350	-93.12	5.869	96.39	0.051	57.26	0.396	-70.03
1800	0.313	-102.0	5.256	90.46	0.054	57.37	0.369	-75.33
2000	0.289	-110.6	4.778	85.58	0.058	58.10	0.348	-80.47
2200	0.278	-118.5	4.394	81.16	0.062	57.66	0.336	-85.37
2400	0.276	-125.0	4.051	77.28	0.066	56.08	0.333	-89.83
2600	0.286	-131.9	3.793	74.34	0.072	60.98	0.316	-92.61
2800	0.293	-136.5	3.571	70.27	0.076	60.21	0.308	-94.44
3000	0.287	-141.6	3.326	67.39	0.083	61.36	0.272	-99.52

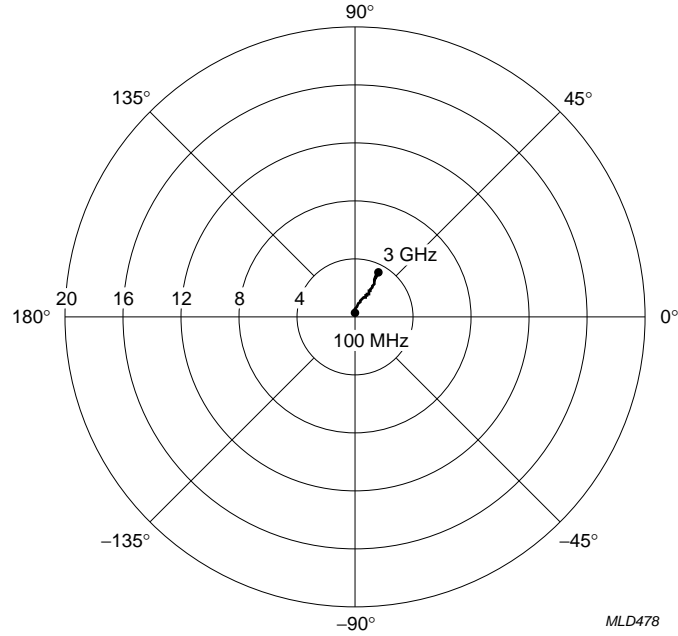
1900 MHz high linear low noise amplifier

BGA2012



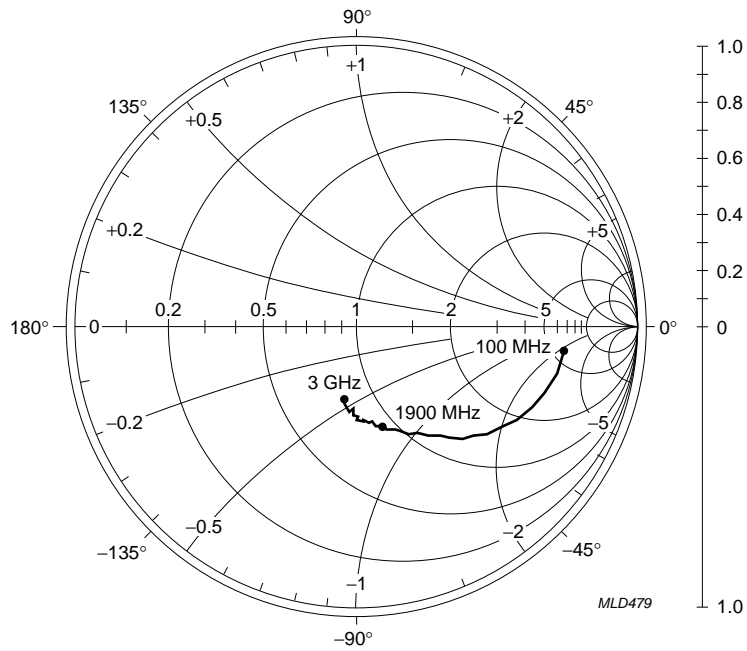
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BGA2012



$I_C = 7 \text{ mA}; V_S = V_C = 3 \text{ V}; P_D = -30 \text{ dBm}; Z_0 = 50 \Omega.$

Fig.10 Common emitter reverse transmission coefficient ( $s_{12}$ ); typical values.



$I_C = 7 \text{ mA}; V_S = V_C = 3 \text{ V}; P_D = -30 \text{ dBm}; Z_0 = 50 \Omega.$

Fig.11 Common emitter output reflection coefficient ( $s_{22}$ ); typical values.



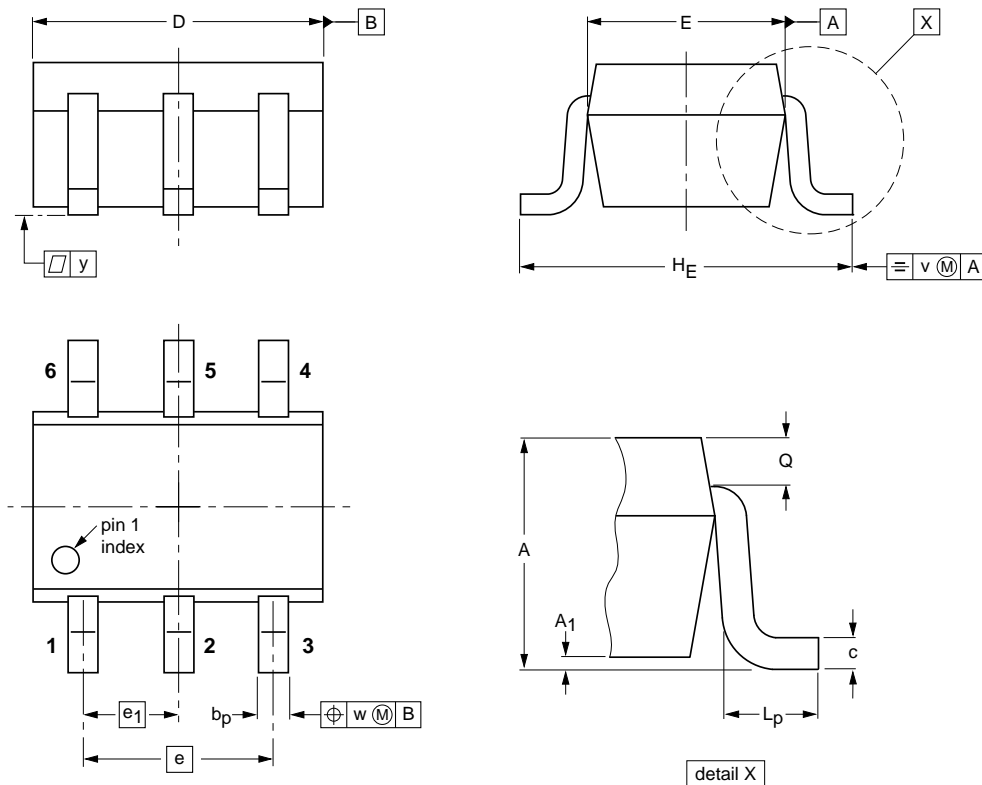
1900 MHz high linear low noise amplifier

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PACKAGE OUTLINE

Plastic surface-mounted package; 6 leads

SOT363



DIMENSIONS (mm are the original dimensions)

UNIT	A	A <sub>1</sub> max	b <sub>p</sub>	c	D	E	e	e <sub>1</sub>	H <sub>E</sub>	L <sub>p</sub>	Q	v	w	y
mm	1.1 0.8	0.1	0.30 0.20	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.25 0.15	0.2	0.2	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT363			SC-88			04-11-08 06-03-16

## 1900 MHz high linear low noise amplifier

BGA2012

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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## BGA2012

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